

# LP2950, LP2951, NCV2951

## DEVICE INFORMATION

Package	Output Voltage				Operating Ambient Temperature Range
	3.0 V	3.3 V	5.0 V	Adjustable	
<b>TO-92</b> <b>Suffix Z</b>	LP2950CZ-3.0 LP2950ACZ-3.0	LP2950CZ-3.3 LP2950ACZ-3.3	LP2950CZ-5.0 LP2950ACZ-5.0	Not Available	$T_A = -40^\circ \text{ to } +125^\circ \text{C}$
<b>DPAK</b> <b>Suffix DT</b>	LP2950CDT-3.0 LP2950ACDT-3.0	LP2950CDT-3.3 LP2950ACDT-3.3	LP2950CDT-5.0 LP2950ACDT-5.0	Not Available	$T_A = -40^\circ \text{ to } +125^\circ \text{C}$
<b>SOIC-8</b>	–	NCV2951ACD-3.3R2	NCV2951ACDR2	NCV2951CDR2	$T_A = -40^\circ \text{ to } +125^\circ \text{C}$
<b>SOIC-8</b> <b>Suffix D</b>	LP2951CD-3.0 LP2951ACD-3.0	LP2951CD-3.3 LP2951ACD-3.3	LP2951CD LP2951ACD	LP2951CD LP2951ACD	$T_A = -40^\circ \text{ to } +125^\circ \text{C}$
<b>Micro8</b> <b>Suffix DM</b>	LP2951CDM-3.0 LP2951ACDM-3.0	LP2951CDM-3.3 LP2951ACDM-3.3	LP2951CDM LP2951ACDM	LP2951CDM LP2951ACDM	$T_A = -40^\circ \text{ to } +125^\circ \text{C}$
<b>DIP-8</b> <b>Suffix N</b>	LP2951CN-3.0 LP2951ACN-3.0	LP2951CN-3.3 LP2951ACN-3.3	LP2951CN LP2951ACN	LP2951CN LP2951ACN	$T_A = -40^\circ \text{ to } +125^\circ \text{C}$

LP2950Cx-xx / LP2951Cxx-xx 1% Output Voltage Precision at  $T_A = 25^\circ \text{C}$   
 LP2950ACx-xx / LP2951ACxx-xx 0.5% Output Voltage Precision at  $T_A = 25^\circ \text{C}$

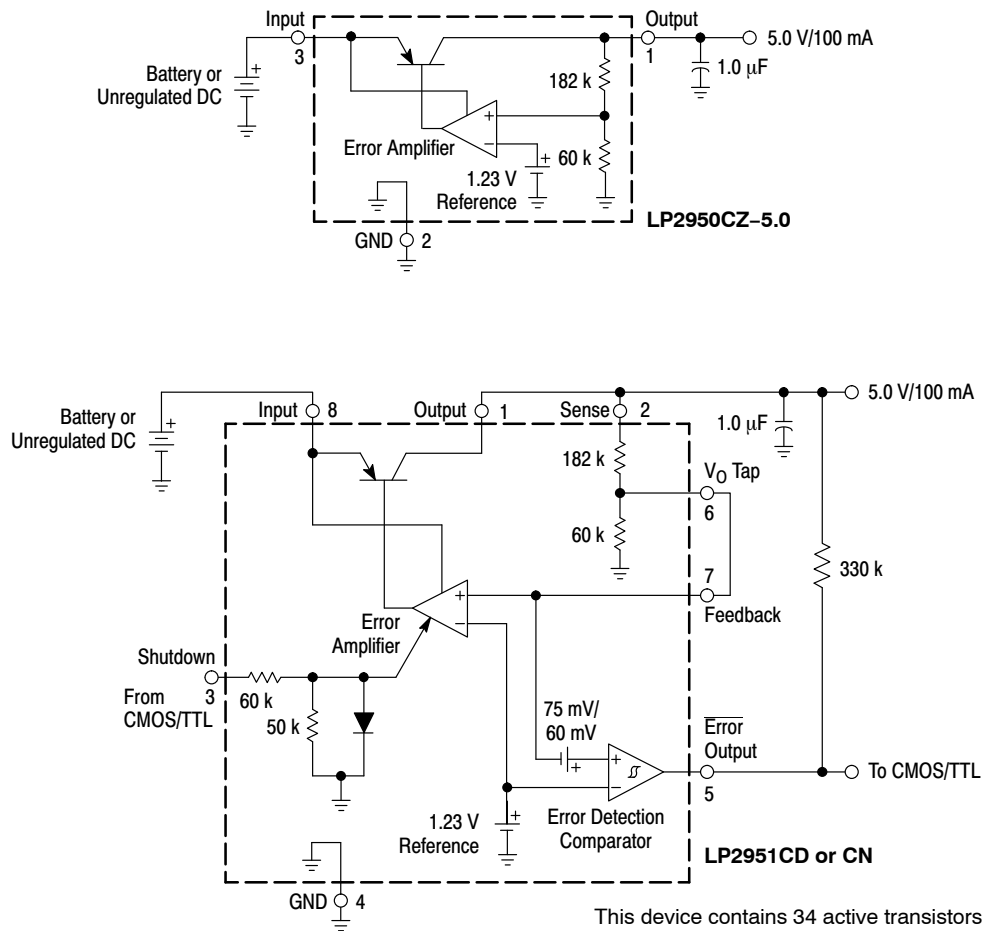


Figure 1. Representative Block Diagrams

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## MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise noted.)

Rating	Symbol	Value	Unit
Input Voltage	V <sub>CC</sub>	30	Vdc
Peak Transient Input Voltage (t < 300 ms)	V <sub>CC</sub>	32	Vdc
Power Dissipation and Thermal Characteristics			
Maximum Power Dissipation	P <sub>D</sub>	Internally Limited	W
Case 751 (SOIC-8) D Suffix			
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	180	°C/W
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	45	°C/W
Case 369A (DPAK) DT Suffix (Note 1)			
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	92	°C/W
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	6.0	°C/W
Case 29 (TO-226AA/TO-92) Z Suffix			
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	160	°C/W
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	83	°C/W
Case 626 N Suffix			
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	105	°C/W
Case 846A (Micro8) DM Suffix			
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	240	°C/W
Feedback Input Voltage	V <sub>fb</sub>	-1.5 to +30	Vdc
Shutdown Input Voltage	V <sub>sd</sub>	-0.3 to +30	Vdc
Error Comparator Output Voltage	V <sub>err</sub>	-0.3 to +30	Vdc
Operating Ambient Temperature Range	T <sub>A</sub>	-40 to +125	°C
Maximum Die Junction Temperature Range	T <sub>J</sub>	+150	°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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## ELECTRICAL CHARACTERISTICS

( $V_{in} = V_O + 1.0\text{ V}$ ,  $I_O = 100\text{ }\mu\text{A}$ ,  $C_O = 1.0\text{ }\mu\text{F}$ ,  $T_A = 25^\circ\text{C}$  [Note 3], unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
Output Voltage, 5.0 V Versions $V_{in} = 6.0\text{ V}$ , $I_O = 100\text{ }\mu\text{A}$ , $T_A = 25^\circ\text{C}$ LP2950C–5.0/LP2951C/NCV2951C* LP2950AC–5.0/LP2951AC/NCV2951AC* $T_A = -40\text{ to }+125^\circ\text{C}$ LP2950C–5.0/LP2951C/NCV2951C* LP2950AC–5.0/LP2951AC/NCV2951AC* $V_{in} = 6.0\text{ to }30\text{ V}$ , $I_O = 100\text{ }\mu\text{A to }100\text{ mA}$ , $T_A = -40\text{ to }+125^\circ\text{C}$ LP2950C–5.0/LP2951C/NCV2951C* LP2950AC–5.0/LP2951AC/NCV2951AC*	$V_O$	4.950 4.975  4.900 4.940  4.880 4.925	5.000 5.000  – –  – –	5.050 5.025  5.100 5.060  5.120 5.075	V
Output Voltage, 3.3 V Versions $V_{in} = 4.3\text{ V}$ , $I_O = 100\text{ }\mu\text{A}$ , $T_A = 25^\circ\text{C}$ LP2950C–3.3/LP2951C–3.3 LP2950AC–3.3/LP2951AC–3.3/NCV2951AC–3.3* $T_A = -40\text{ to }+125^\circ\text{C}$ LP2950C–3.3/LP2951C–3.3 LP2950AC–3.3/LP2951AC–3.3/NCV2951AC–3.3* $V_{in} = 4.3\text{ to }30\text{ V}$ , $I_O = 100\text{ }\mu\text{A to }100\text{ mA}$ , $T_A = -40\text{ to }+125^\circ\text{C}$ LP2950C–3.3/LP2951C–3.3 LP2950AC–3.3/LP2951AC–3.3/NCV2951AC–3.3*	$V_O$	3.267 3.284  3.234 3.260  3.221 3.254	3.300 3.300  – –  – –	3.333 3.317  3.366 3.340  3.379 3.346	V
Output Voltage, 3.0 V Versions $V_{in} = 4.0\text{ V}$ , $I_O = 100\text{ }\mu\text{A}$ , $T_A = 25^\circ\text{C}$ LP2950C–3.0/LP2951C–3.0 LP2950AC–3.0/LP2951AC–3.0 $T_A = -40\text{ to }+125^\circ\text{C}$ LP2950C–3.0/LP2951C–3.0 LP2950AC–3.0/LP2951AC–3.0 $V_{in} = 4.0\text{ to }30\text{ V}$ , $I_O = 100\text{ }\mu\text{A to }100\text{ mA}$ , $T_A = -40\text{ to }+125^\circ\text{C}$ LP2950C–3.0/LP2951C–3.0 LP2950AC–3.0/LP2951AC–3.0	$V_O$	2.970 2.985  2.940 2.964  2.928 2.958	3.000 3.000  – –  – –	3.030 3.015  3.060 3.036  3.072 3.042	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- The Junction-to-Ambient Thermal Resistance is determined by PCB copper area per Figure 29.
- This device series contains ESD protection and exceeds the following tests:  
 Human Body Model (HBM), 2000 V, Class 2, JESD22 A114–C  
 Machine Model (MM), 200 V, Class B, JESD22 A115–A  
 Charged Device Model (CDM), 2000 V, Class IV, JESD22 C101–C
- Low duty pulse techniques are used during test to maintain junction temperature as close to ambient as possible.
- $V_{O(nom)}$  is the part number voltage option.
- Noise tests on the LP2951 are made with a 0.01  $\mu\text{F}$  capacitor connected across Pins 7 and 1.
- Latch-up Current Maximum Rating tested per JEDEC standard: JESD78  
 – Inputs Low: passing positive current 100 mA and negative current –100 mA  
 – Inputs High: passing positive current 100 mA and negative current –10 mA.

\*NCV prefix is for automotive and other applications requiring site and change control.

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## ELECTRICAL CHARACTERISTICS (continued)

( $V_{in} = V_O + 1.0\text{ V}$ ,  $I_O = 100\text{ }\mu\text{A}$ ,  $C_O = 1.0\text{ }\mu\text{F}$ ,  $T_A = 25^\circ\text{C}$  [Note 9], unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
Line Regulation ( $V_{in} = V_{O(nom)} + 1.0\text{ V}$ to $30\text{ V}$ ) (Note 10) LP2950C-XX/LP2951C/LP2951C-XX/NCV2951C* LP2950AC-XX/LP2951AC/LP2951AC-XX/NCV2951AC*	$Reg_{line}$	– –	0.08 0.04	0.20 0.10	%
Load Regulation ( $I_O = 100\text{ }\mu\text{A}$ to $100\text{ mA}$ ) LP2950C-XX/LP2951C/LP2951C-XX/NCV2951C* LP2950AC-XX/LP2951AC/LP2951AC-XX/NCV2951AC*	$Reg_{load}$	– –	0.13 0.05	0.20 0.10	%
Dropout Voltage $I_O = 100\text{ }\mu\text{A}$ $I_O = 100\text{ mA}$	$V_I - V_O$	– –	30 350	80 450	mV
Supply Bias Current $I_O = 100\text{ }\mu\text{A}$ $I_O = 100\text{ mA}$	$I_{CC}$	– –	93 4.0	120 12	$\mu\text{A}$ mA
Dropout Supply Bias Current ( $V_{in} = V_{O(nom)} - 0.5\text{ V}$ , $I_O = 100\text{ }\mu\text{A}$ ) (Note 10)	$I_{CCdropout}$	–	110	170	$\mu\text{A}$
Current Limit ( $V_O$ Shorted to Ground)	$I_{Limit}$	–	220	300	mA
Thermal Regulation	$Reg_{thermal}$	–	0.05	0.20	%/W
Output Noise Voltage (10 Hz to 100 kHz) (Note 11) $C_L = 1.0\text{ }\mu\text{F}$ $C_L = 100\text{ }\mu\text{F}$	$V_n$	– –	126 56	– –	$\mu\text{V}_{rms}$

### LP2951A/LP2951AC Only

Reference Voltage ( $T_A = 25^\circ\text{C}$ ) LP2951C/LP2951C-XX/NCV2951C* LP2951AC/LP2951AC-XX/NCV2951AC*	$V_{ref}$	1.210 1.220	1.235 1.235	1.260 1.250	V
Reference Voltage ( $T_A = -40$ to $+125^\circ\text{C}$ ) LP2951C/LP2951C-XX/NCV2951C* LP2951AC/LP2951AC-XX/NCV2951AC*	$V_{ref}$	1.200 1.200	– –	1.270 1.260	V
Reference Voltage ( $T_A = -40$ to $+125^\circ\text{C}$ ) $I_O = 100\text{ }\mu\text{A}$ to $100\text{ mA}$ , $V_{in} = 23$ to $30\text{ V}$ LP2951C/LP2951C-XX/NCV2951C* LP2951AC/LP2951AC-XX/NCV2951AC*	$V_{ref}$	1.185 1.190	– –	1.285 1.270	V
Feedback Pin Bias Current	$I_{FB}$	–	15	40	nA

### Error Comparator

Output Leakage Current ( $V_{OH} = 30\text{ V}$ )	$I_{lkg}$	–	0.01	1.0	$\mu\text{A}$
Output Low Voltage ( $V_{in} = 4.5\text{ V}$ , $I_{OL} = 400\text{ }\mu\text{A}$ )	$V_{OL}$	–	150	250	mV
Upper Threshold Voltage ( $V_{in} = 6.0\text{ V}$ )	$V_{thu}$	40	45	–	mV
Lower Threshold Voltage ( $V_{in} = 6.0\text{ V}$ )	$V_{thl}$	–	60	95	mV
Hysteresis ( $V_{in} = 6.0\text{ V}$ )	$V_{hy}$	–	15	–	mV

### Shutdown Input

Input Logic Voltage Logic "0" (Regulator "On") Logic "1" (Regulator "Off")	$V_{shdn}$	0 2.0	– –	0.7 30	V
Shutdown Pin Input Current $V_{shdn} = 2.4\text{ V}$ $V_{shdn} = 30\text{ V}$	$I_{shdn}$	– –	35 450	50 600	$\mu\text{A}$
Regulator Output Current in Shutdown Mode ( $V_{in} = 30\text{ V}$ , $V_{shdn} = 2.0\text{ V}$ , $V_O = 0$ , Pin 6 Connected to Pin 7)	$I_{off}$	–	3.0	10	$\mu\text{A}$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

7. The Junction-to-Ambient Thermal Resistance is determined by PCB copper area per Figure 29.

8. ESD data available upon request.

9. Low duty pulse techniques are used during test to maintain junction temperature as close to ambient as possible.

10.  $V_{O(nom)}$  is the part number voltage option.

11. Noise tests on the LP2951 are made with a  $0.01\text{ }\mu\text{F}$  capacitor connected across Pins 7 and 1.

\*NCV prefix is for automotive and other applications requiring site and change control.

## DEFINITIONS

**Dropout Voltage** – The input/output voltage differential at which the regulator output no longer maintains regulation against further reductions in input voltage. Measured when the output drops 100 mV below its nominal value (which is measured at 1.0 V differential), dropout voltage is affected by junction temperature, load current and minimum input supply requirements.

**Line Regulation** – The change in output voltage for a change in input voltage. The measurement is made under conditions of low dissipation or by using pulse techniques such that average chip temperature is not significantly affected.

**Load Regulation** – The change in output voltage for a change in load current at constant chip temperature.

**Maximum Power Dissipation** – The maximum total device dissipation for which the regulator will operate within specifications.

**Bias Current** – Current which is used to operate the regulator chip and is not delivered to the load.

**Output Noise Voltage** – The RMS ac voltage at the output, with constant load and no input ripple, measured over a specified frequency range.

**Leakage Current** – Current drawn through a bipolar transistor collector–base junction, under a specified collector voltage, when the transistor is “off”.

**Upper Threshold Voltage** – Voltage applied to the comparator input terminal, below the reference voltage which is applied to the other comparator input terminal, which causes the comparator output to change state from a logic “0” to “1”.

**Lower Threshold Voltage** – Voltage applied to the comparator input terminal, below the reference voltage which is applied to the other comparator input terminal, which causes the comparator output to change state from a logic “1” to “0”.

**Hysteresis** – The difference between Lower Threshold voltage and Upper Threshold voltage.

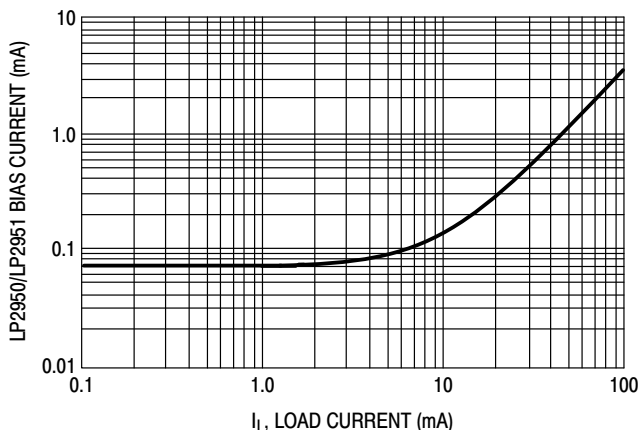


Figure 2. Quiescent Current

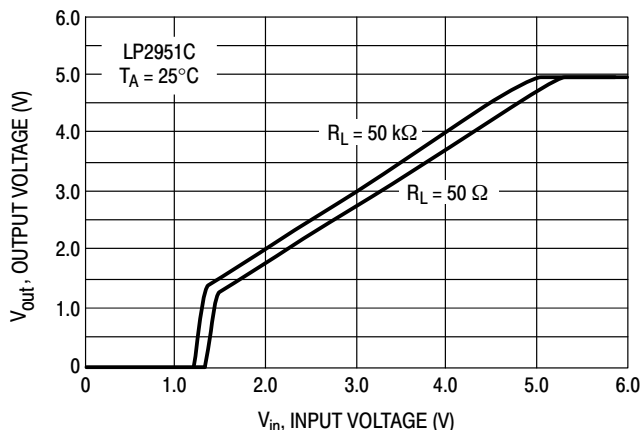


Figure 3. 5.0 V Dropout Characteristics over Load

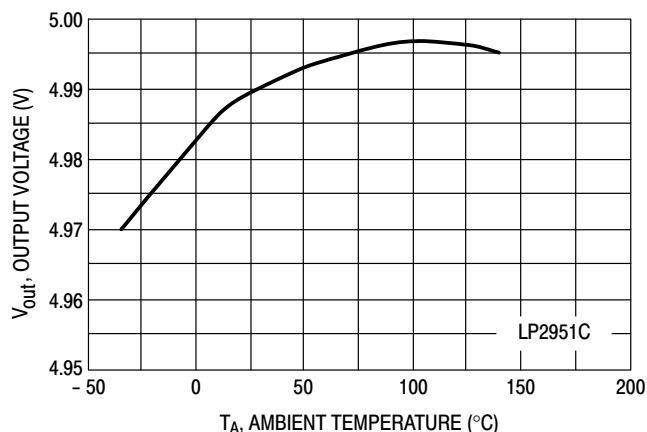


Figure 4. Output Voltage versus Temperature

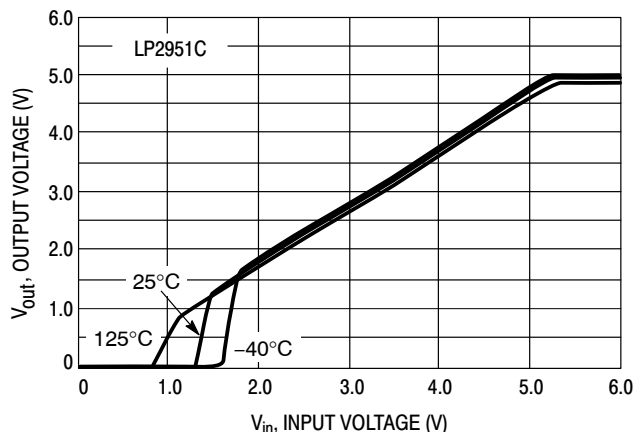


Figure 5. 5.0 V Dropout Characteristics with  $R_L = 50 \Omega$

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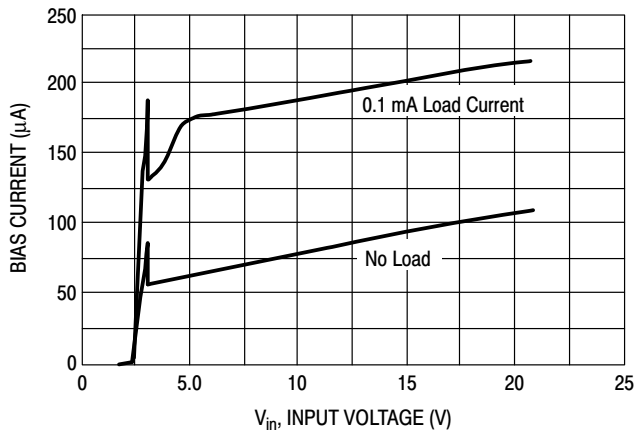


Figure 6. Input Current

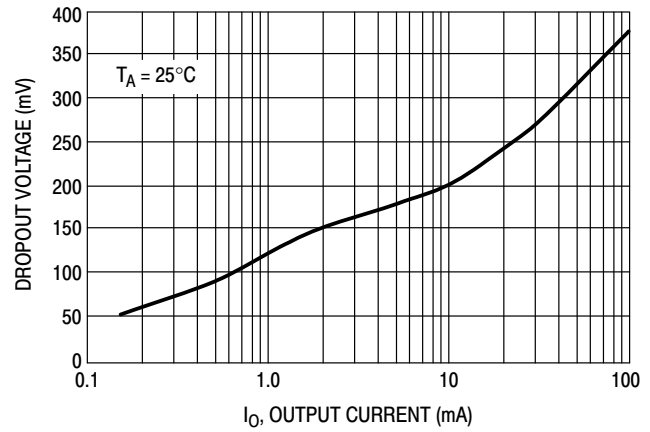


Figure 7. Dropout Voltage versus Output Current

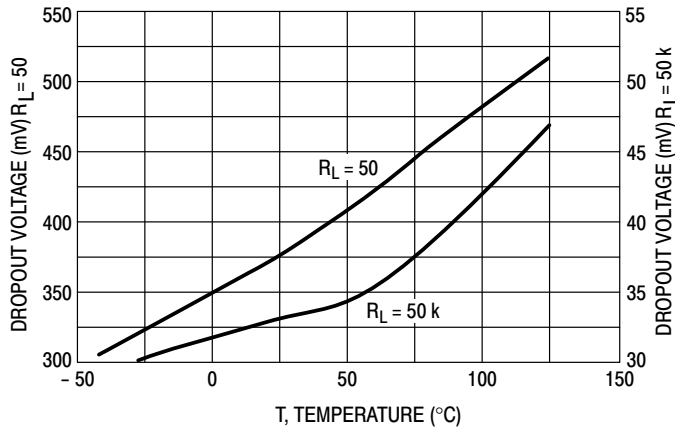


Figure 8. Dropout Voltage versus Temperature

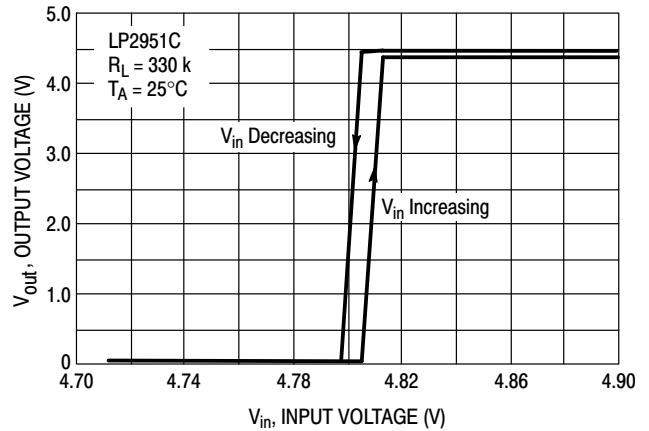


Figure 9. Error Comparator Output

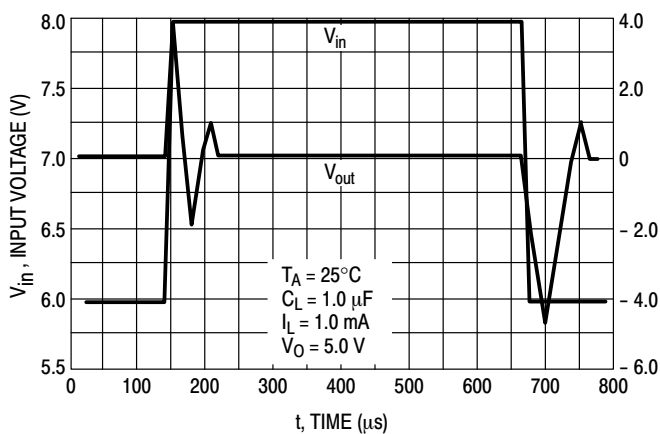


Figure 10. Line Transient Response

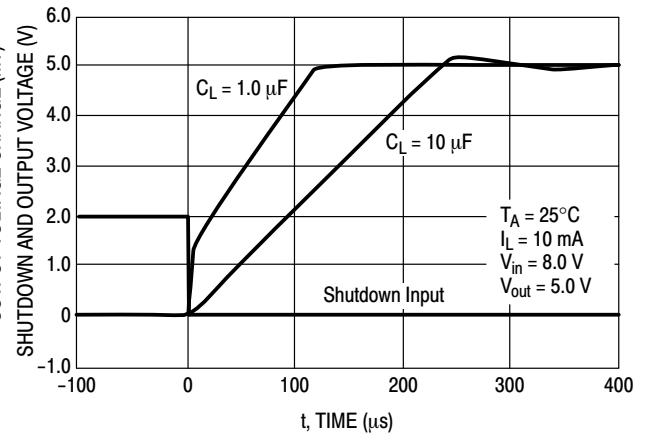


Figure 11. LP2951 Enable Transient

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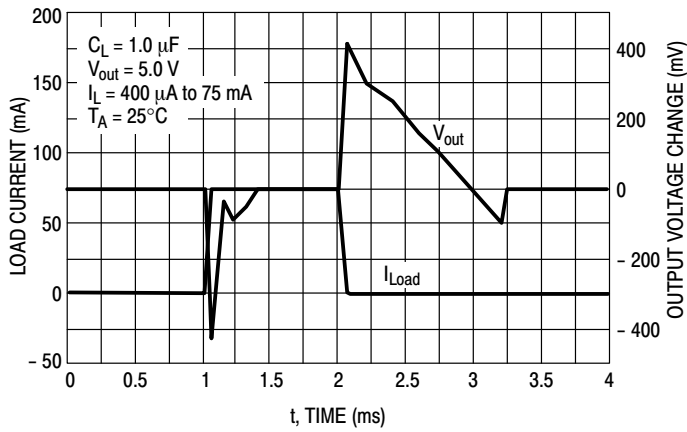


Figure 12. Load Transient Response

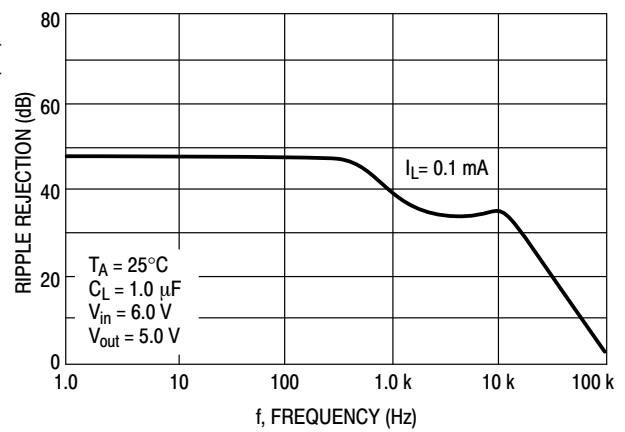


Figure 13. Ripple Rejection

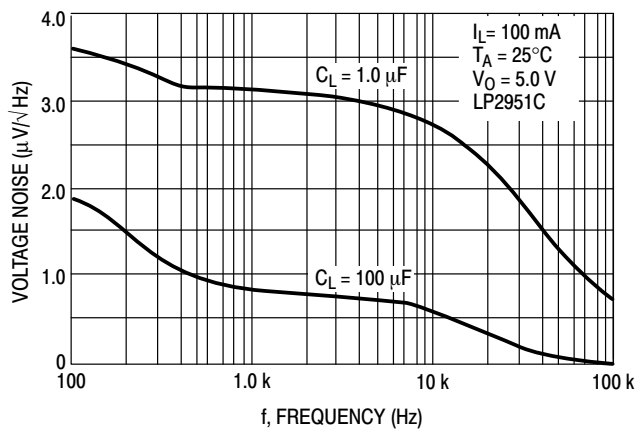


Figure 14. Output Noise

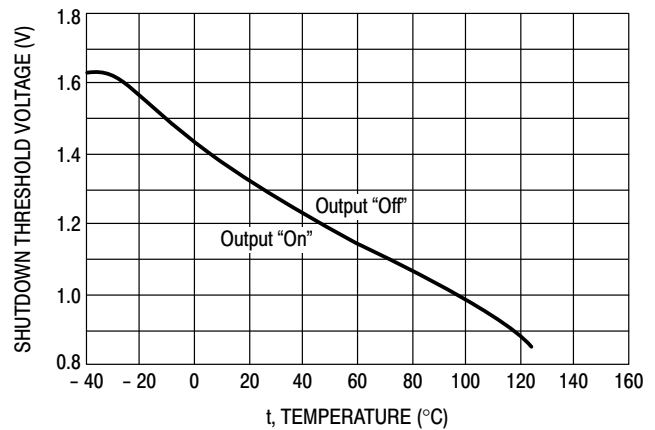


Figure 15. Shutdown Threshold Voltage versus Temperature

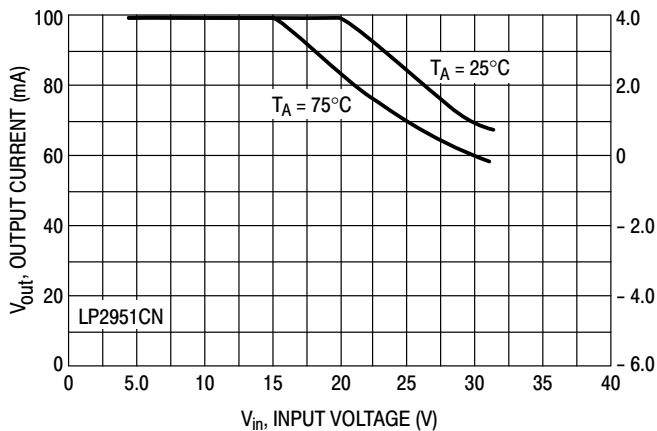


Figure 16. Maximum Rated Output Current

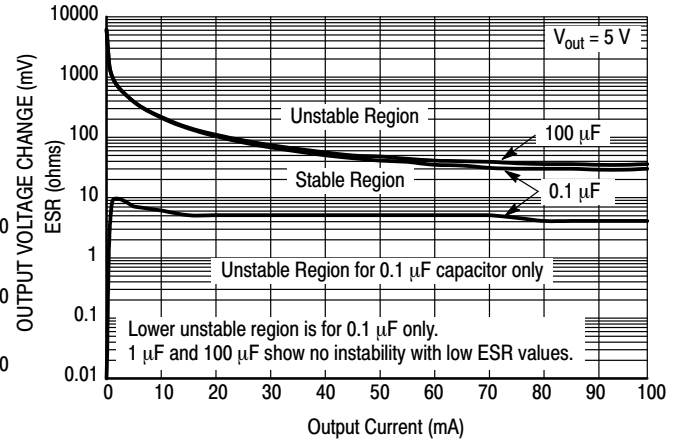


Figure 17. Output Stability versus Output Capacitor Change

## APPLICATIONS INFORMATION

### Introduction

The LP2950/LP2951 regulators are designed with internal current limiting and thermal shutdown making them user-friendly. Typical application circuits for the LP2950 and LP2951 are shown in Figures 20 through 28.

These regulators are not internally compensated and thus require a 1.0  $\mu\text{F}$  (or greater) capacitance between the LP2950/LP2951 output terminal and ground for stability. Most types of aluminum, tantalum or multilayer ceramic will perform adequately. Solid tantalums or appropriate multilayer ceramic capacitors are recommended for operation below 25°C.

At lower values of output current, less output capacitance is required for output stability. The capacitor can be reduced to 0.33  $\mu\text{F}$  for currents less than 10 mA, or 0.1  $\mu\text{F}$  for currents below 1.0 mA. Using the 8 pin versions at voltages less than 5.0 V operates the error amplifier at lower values of gain, so that more output capacitance is needed for stability. For the worst case operating condition of a 100 mA load at 1.23 V output (output Pin 1 connected to the feedback Pin 7) a minimum capacitance of 3.3  $\mu\text{F}$  is recommended.

The LP2950 will remain stable and in regulation when operated with no output load. When setting the output voltage of the LP2951 with external resistors, the resistance values should be chosen to draw a minimum of 1.0  $\mu\text{A}$ .

A bypass capacitor is recommended across the LP2950/LP2951 input to ground if more than 4 inches of wire connects the input to either a battery or power supply filter capacitor.

Input capacitance at the LP2951 Feedback Pin 7 can create a pole, causing instability if high value external resistors are used to set the output voltage. Adding a 100 pF capacitor between the Output Pin 1 and the Feedback Pin 7 and increasing the output filter capacitor to at least 3.3  $\mu\text{F}$  will stabilize the feedback loop.

### Error Detection Comparator

The comparator switches to a positive logic low whenever the LP2951 output voltage falls more than approximately 5.0% out of regulation. This value is the comparator's designed-in offset voltage of 60 mV divided by the 1.235 V internal reference. As shown in the representative block diagram. This trip level remains 5.0% below normal regardless of the value of regulated output voltage. For example, the error flag trip level is 4.75 V for a normal 5.0 V regulated output, or 9.50 V for a 10 V output voltage.

Figure 2 is a timing diagram which shows the  $\overline{\text{ERROR}}$  signal and the regulated output voltage as the input voltage

to the LP2951 is ramped up and down. The  $\overline{\text{ERROR}}$  signal becomes valid (low) at about 1.3 V input. It goes high when the input reaches about 5.0 V ( $V_{\text{out}}$  exceeds about 4.75 V). Since the LP2951's dropout voltage is dependent upon the load current (refer to the curve in the Typical Performance Characteristics), the input voltage trip point will vary with load current. The output voltage trip point does not vary with load.

The error comparator output is an open collector which requires an external pullup resistor. This resistor may be returned to the output or some other voltage within the system. The resistance value should be chosen to be consistent with the 400  $\mu\text{A}$  sink capability of the error comparator. A value between 100 k $\Omega$  and 1.0 M $\Omega$  is suggested. No pullup resistance is required if this output is unused.

When operated in the power down mode ( $V_{\text{in}} = 0 \text{ V}$ ), the error comparator output will go high if it has been pulled up to an external supply (the output transistor is in high impedance state). To avoid this invalid response, the error comparator output should be pulled up to  $V_{\text{out}}$  (see Figure 18).

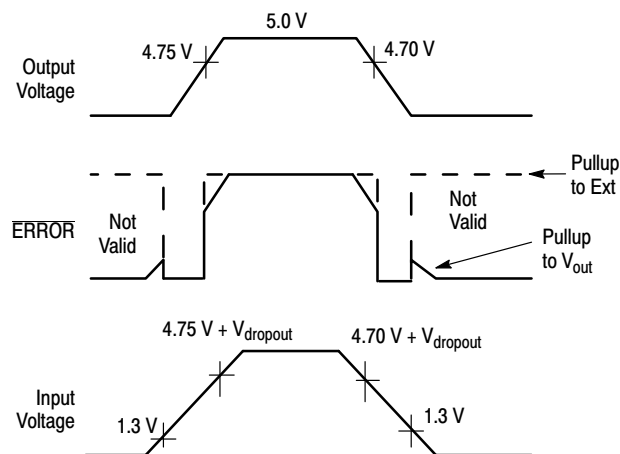


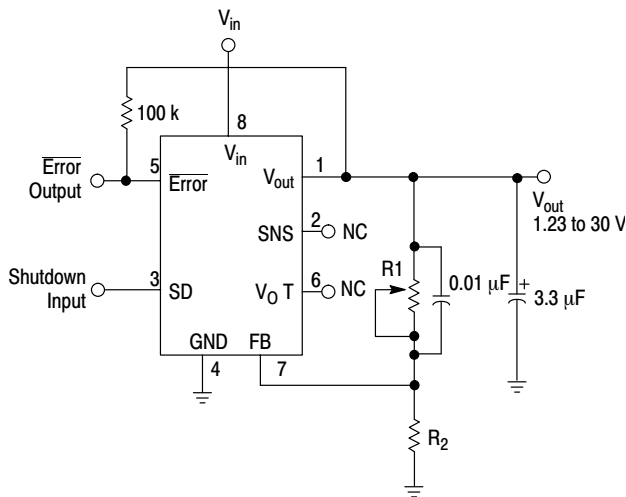
Figure 18.  $\overline{\text{ERROR}}$  Output Timing

### Programming the Output Voltage (LP2951)

The LP2951CX may be pin-strapped for the nominal fixed output voltage using its internal voltage divider by tying Pin 1 (output) to Pin 2 (sense) and Pin 7 (feedback) to Pin 6 (5.0 V tap). Alternatively, it may be programmed for any output voltage between its 1.235 reference voltage and its 30 V maximum rating. An external pair of resistors is required, as shown in Figure 19.



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**Figure 19. Adjustable Regulator**

The complete equation for the output voltage is:

$$V_{out} = V_{ref} (1 + R1/R2) + I_{FB} R1$$

where  $V_{ref}$  is the nominal 1.235 V reference voltage and  $I_{FB}$  is the feedback pin bias current, nominally  $-20$  nA. The minimum recommended load current of  $1.0$   $\mu$ A forces an upper limit of  $1.2$  M $\Omega$  on the value of  $R2$ , if the regulator must work with no load.  $I_{FB}$  will produce a 2% typical error in  $V_{out}$  which may be eliminated at room temperature by adjusting  $R1$ . For better accuracy, choosing  $R2 = 100$  k reduces this error to 0.17% while increasing the resistor program current to  $12$   $\mu$ A. Since the LP2951 typically draws  $75$   $\mu$ A at no load with Pin 2 open circuited, the extra  $12$   $\mu$ A of current drawn is often a worthwhile tradeoff for eliminating the need to set output voltage in test.

### Output Noise

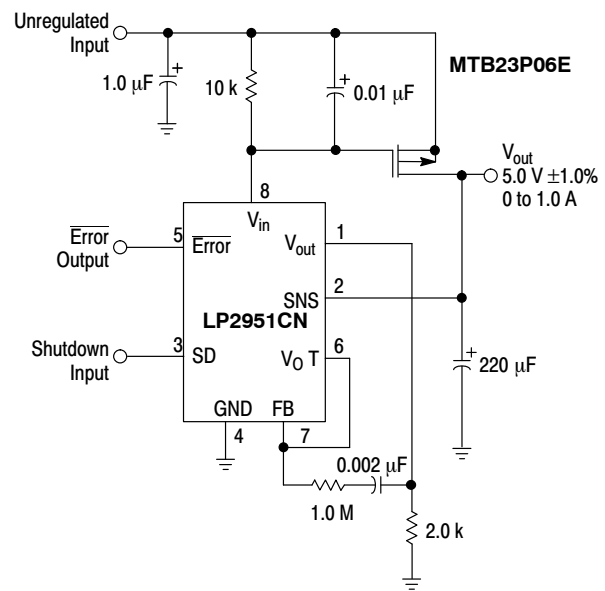
In many applications it is desirable to reduce the noise present at the output. Reducing the regulator bandwidth by increasing the size of the output capacitor is the only method

for reducing noise on the 3 lead LP2950. However, increasing the capacitor from  $1.0$   $\mu$ F to  $220$   $\mu$ F only decreases the noise from  $430$   $\mu$ V to  $160$   $\mu$ Vrms for a  $100$  kHz bandwidth at the  $5.0$  V output.

Noise can be reduced fourfold by a bypass capacitor across  $R1$ , since it reduces the high frequency gain from 4 to unity. Pick

$$C_{Bypass} \approx \frac{1}{2\pi R1 \times 200 \text{ Hz}}$$

or about  $0.01$   $\mu$ F. When doing this, the output capacitor must be increased to  $3.3$   $\mu$ F to maintain stability. These changes reduce the output noise from  $430$   $\mu$ V to  $126$   $\mu$ Vrms for a  $100$  kHz bandwidth at  $5.0$  V output. With bypass capacitor added, noise no longer scales with output voltage so that improvements are more dramatic at higher output voltages.



**Figure 20. 1.0 A Regulator with 1.2 V Dropout**

# LP2950, LP2951, NCV2951

## TYPICAL APPLICATIONS

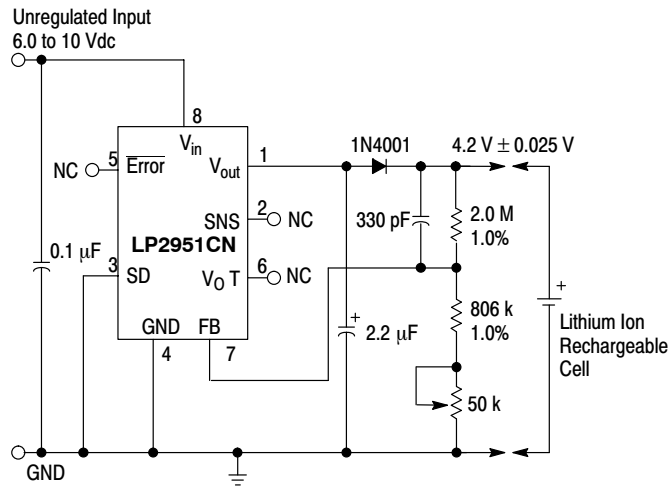


Figure 21. Lithium Ion Battery Cell Charger

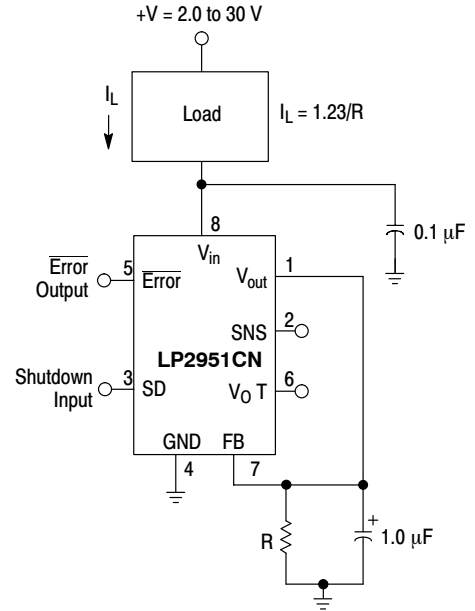
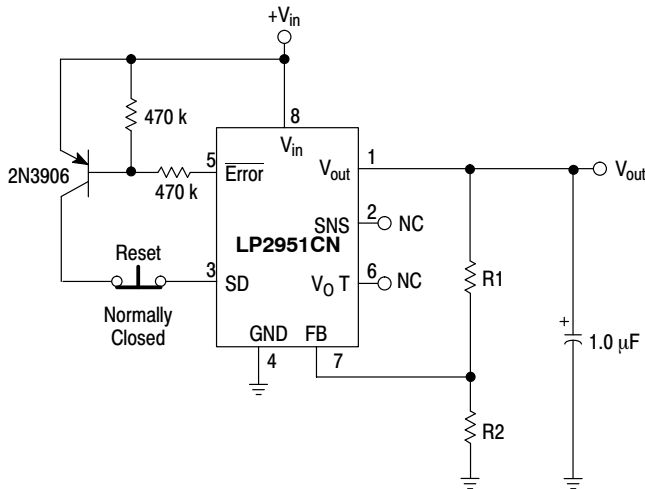


Figure 22. Low Drift Current Sink



Error flag occurs when  $V_{in}$  is too low to maintain  $V_{out}$ , or if  $V_{out}$  is reduced by excessive load current.

Figure 23. Latch Off When Error Flag Occurs

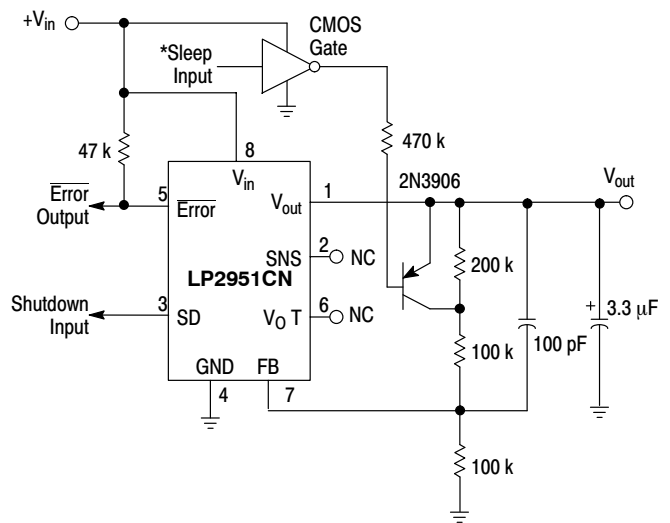
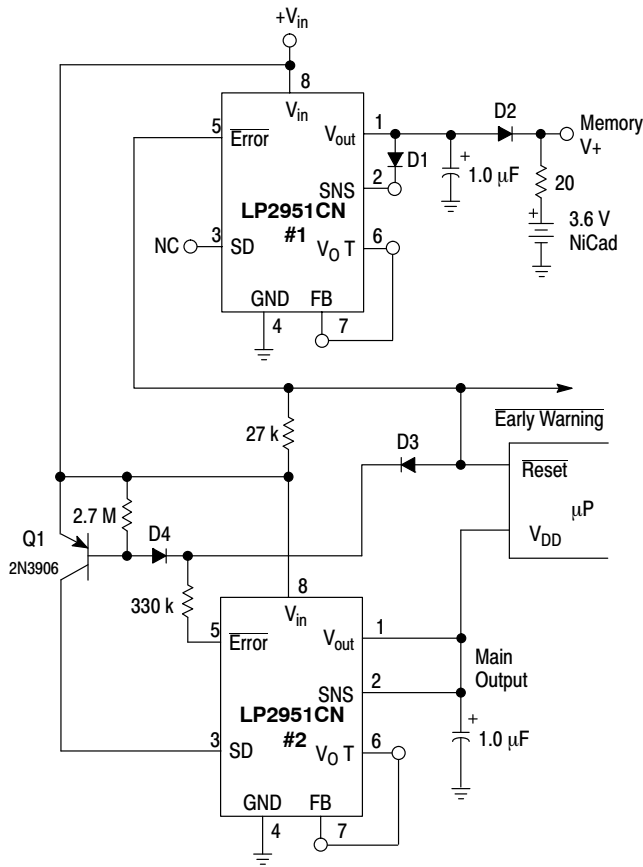


Figure 24. 5.0 V Regulator with 2.5 V Sleep Function

## LP2950, LP2951, NCV2951



All diodes are 1N4148.

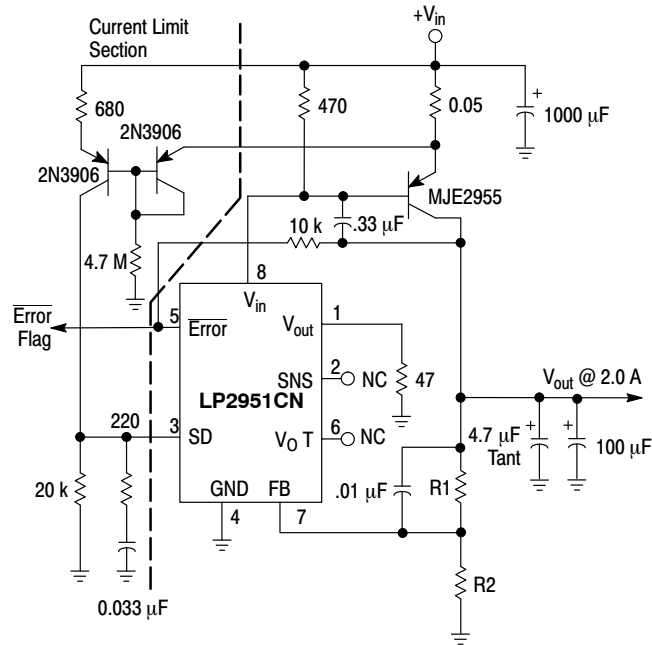
Early Warning flag on low input voltage.

Main output latches off at lower input voltages.

Battery backup on auxiliary output.

Operation: Regulator #1's  $V_{out}$  is programmed one diode drop above 5.0 V. Its error flag becomes active when  $V_{in} \leq 5.7$  V. When  $V_{in}$  drops below 5.3 V, the error flag of regulator #2 becomes active and via Q1 latches the main output "off". When  $V_{in}$  again exceeds 5.7 V, regulator #1 is back in regulation and the early warning signal rises, unlatching regulator #2 via D3.

Figure 25. Regulator with Early Warning and Auxiliary Output



$$V_{out} = 1.25V (1.0 + R1/R2)$$

For 5.0 V output, use internal resistors. Wire Pin 6 to 7, and wire Pin 2 to  $+V_{out}$  Bus.

Figure 26. 2.0 A Low Dropout Regulator

## LP2950, LP2951, NCV2951

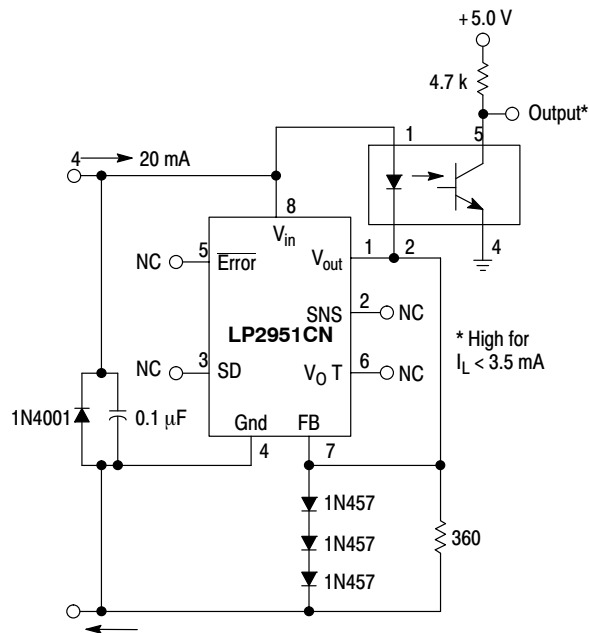


Figure 27. Open Circuit Detector for 4.0 to 20 mA Current Loop

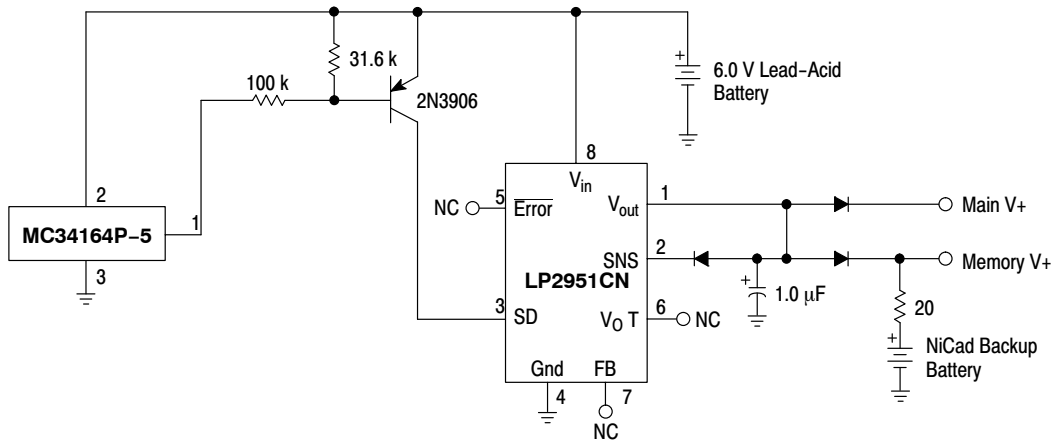


Figure 28. Low Battery Disconnect

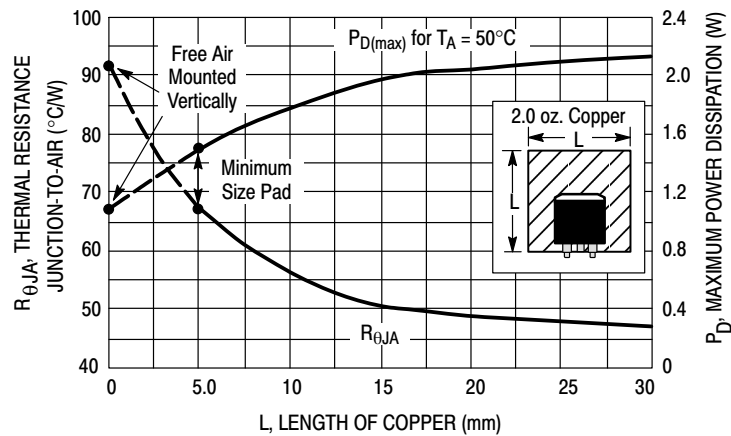


Figure 29. DPAK Thermal Resistance and Maximum Power Dissipation versus PCB Copper Length

# LP2950, LP2951, NCV2951

## ORDERING INFORMATION (LP2950)

Part Number	Output Voltage (Volts)	Tolerance (%)	Package	Shipping†
LP2950CZ-3.0G	3.0	1.0	TO-92 (Pb-Free)	2000 Units / Bag
LP2950CZ-3.0RAG	3.0	1.0	TO-92 (Pb-Free)	2000 Units / Tape & Reel
LP2950ACZ-3.0G	3.0	0.5	TO-92 (Pb-Free)	2000 Units / Bag
LP2950ACZ-3.0RAG	3.0	0.5	TO-92 (Pb-Free)	2000 Units / Tape & Reel
LP2950CZ-3.3G	3.3	1.0	TO-92 (Pb-Free)	2000 Units / Bag
LP2950CZ-3.3RAG	3.3	1.0	TO-92 (Pb-Free)	2000 Units / Tape & Reel
LP2950ACZ-3.3G	3.3	0.5	TO-92 (Pb-Free)	2000 Units / Bag
LP2950ACZ-3.3RAG	3.3	0.5	TO-92 (Pb-Free)	2000 Units / Tape & Reel
LP2950CZ-5.0G	5.0	1.0	TO-92 (Pb-Free)	2000 Units / Bag
LP2950CZ-5.0RAG	5.0	1.0	TO-92 (Pb-Free)	2000 Units / Tape & Reel
LP2950CZ-5.0RPG	5.0	1.0	TO-92 (Pb-Free)	2000 Units / Ammo Pack
LP2950ACZ-5.0G	5.0	0.5	TO-92 (Pb-Free)	2000 Units / Bag
LP2950ACZ-5.0RAG	5.0	0.5	TO-92 (Pb-Free)	2000 Units / Tape & Reel
LP2950CDT-3.0G	3.0	1.0	DPAK (Pb-Free)	75 Units / Rail
LP2950CDT-3.0RKG	3.0	1.0	DPAK (Pb-Free)	2500 Units / Tape & Reel
LP2950ACDT-3.0G	3.0	0.5	DPAK (Pb-Free)	75 Units / Rail
LP2950ACDT-3.0RKG	3.0	0.5	DPAK (Pb-Free)	2500 Units / Tape & Reel
LP2950CDT-3.3G	3.3	1.0	DPAK (Pb-Free)	75 Units / Rail
LP2950CDT-3.3RKG	3.3	1.0	DPAK (Pb-Free)	2500 Units / Tape & Reel
LP2950ACDT-3.3RG	3.3	0.5	DPAK (Pb-Free)	2500 Units / Tape & Reel
LP2950CDT-5.0G	5.0	1.0	DPAK (Pb-Free)	75 Units / Rail
LP2950CDT-5.0RKG	5.0	1.0	DPAK (Pb-Free)	2500 Units / Tape & Reel
LP2950ACDT-5.0G	5.0	0.5	DPAK (Pb-Free)	75 Units / Rail
LP2950ACDT-5.0RKG	5.0	0.5	DPAK (Pb-Free)	2500 Units / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## LP2950, LP2951, NCV2951

### ORDERING INFORMATION (LP2951)

Part Number	Output Voltage (Volts)	Tolerance (%)	Package	Shipping†
LP2951CD-3.0G	3.0	1.0	SOIC-8 (Pb-Free)	98 Units / Rail
LP2951CD-3.0R2G	3.0	1.0	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
LP2951ACD-3.0G	3.0	0.5	SOIC-8 (Pb-Free)	98 Units / Rail
LP2951ACD-3.0R2G	3.0	0.5	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
LP2951CD-3.3G	3.3	1.0	SOIC-8 (Pb-Free)	98 Units / Rail
LP2951CD-3.3R2G	3.3	1.0	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
LP2951ACD-3.3G	3.3	0.5	SOIC-8 (Pb-Free)	98 Units / Rail
LP2951ACD-3.3R2G	3.3	0.5	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
LP2951CDG	5.0 or Adj.	1.0	SOIC-8 (Pb-Free)	98 Units / Rail
LP2951CDR2G	5.0 or Adj.	1.0	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
LP2951ACDG	5.0 or Adj.	0.5	SOIC-8 (Pb-Free)	98 Units / Rail
LP2951ACDR2G	5.0 or Adj.	0.5	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
LP2951CDM-3.0R2G	3.0	1.0	Micro8 (Pb-Free)	4000 Units / Tape & Reel
LP2951ACDM-3.0RG	3.0	0.5	Micro8 (Pb-Free)	4000 Units / Tape & Reel
LP2951CDM-3.3R2G	3.3	1.0	Micro8 (Pb-Free)	4000 Units / Tape & Reel
LP2951ACDM-3.3RG	3.3	0.5	Micro8 (Pb-Free)	4000 Units / Tape & Reel
LP2951CDMR2G	5.0 or Adj.	1.0	Micro8 (Pb-Free)	4000 Units / Tape & Reel
LP2951ACDMR2G	5.0 or Adj.	0.5	Micro8 (Pb-Free)	4000 Units / Tape & Reel
LP2951ACN-3.0G	3.0	0.5	PDIP-8 (Pb-Free)	50 Units / Rail
LP2951CN-3.3G	3.3	1.0	PDIP-8 (Pb-Free)	50 Units / Rail
LP2951ACN-3.3G	3.3	0.5	PDIP-8 (Pb-Free)	50 Units / Rail
LP2951CNG	5.0 or Adj.	1.0	PDIP-8 (Pb-Free)	50 Units / Rail
LP2951ACNG	5.0 or Adj.	0.5	PDIP-8 (Pb-Free)	50 Units / Rail

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## LP2950, LP2951, NCV2951

### ORDERING INFORMATION (NCV2951)

Part Number	Output Voltage (Volts)	Tolerance (%)	Package	Shipping <sup>†</sup>
NCV2951ACD3.3R2G*	3.3	0.5	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
NCV2951ACDR2G*	5.0 or Adj.	0.5	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
NCV2951CDR2G*	5.0 or Adj.	1.0	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel
NCV2951ACDMR2G*	5.0 or Adj.	0.5	Micro8 (Pb-Free)	4000 Units / Tape & Reel

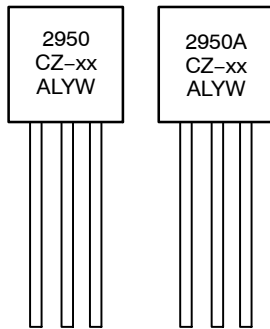
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

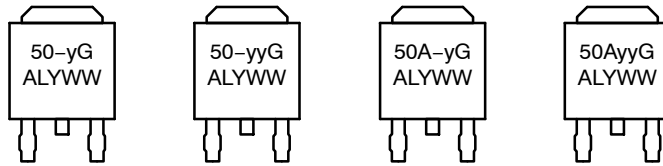
# LP2950, LP2951, NCV2951

## MARKING DIAGRAMS

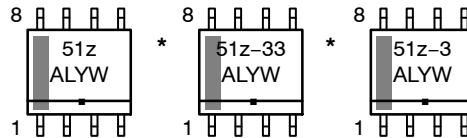
**TO-92  
CASE 029**



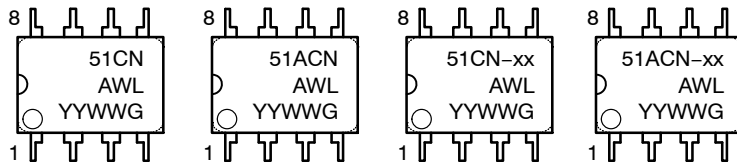
**DPAK  
CASE 369C**



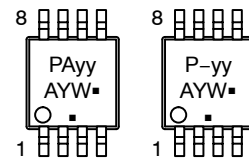
**SOIC-8  
CASE 751**



**PDIP-8  
CASE 626**



**Micro8  
CASE 846A**



xx = 3.0, 3.3, or 5.0  
y = 3 or 5  
yy = 30, 33, or 50  
z = A or C  
A = Assembly Location  
WL, L = Wafer Lot  
YY, Y = Year  
WW, W = Work Week  
G = Pb-Free Package  
▪ = Pb-Free Package  
(Note: Microdot may be in either location)

\*This marking diagram also applies to NCV2951.



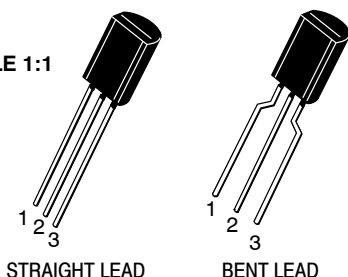
# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

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SCALE 1:1



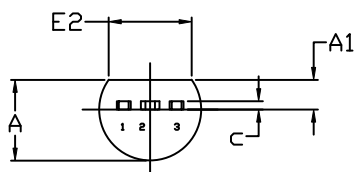
STRAIGHT LEAD

BENT LEAD

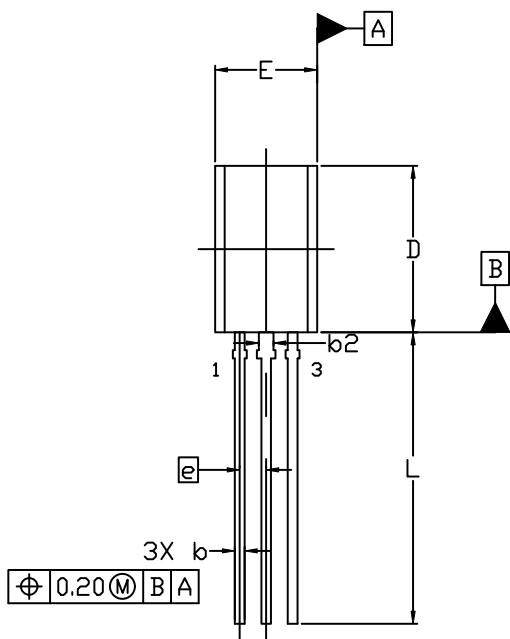
TO-92 (TO-226) 1 WATT  
CASE 29-10  
ISSUE D

DATE 05 MAR 2021

### STRAIGHT LEAD



END VIEW



TOP VIEW

#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS.
4. DIMENSION b AND b2 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 0.20. DIMENSION b2 LOCATED ABOVE THE DAMBAR PORTION OF MIDDLE LEAD.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	3.75	3.90	4.05
A1	1.28	1.43	1.58
b	0.38	0.465	0.55
b2	0.62	0.70	0.78
c	0.35	0.40	0.45
D	7.85	8.00	8.15
E	4.75	4.90	5.05
E2	3.90	---	---
e	1.27 BSC		
L	13.80	14.00	14.20

### STYLES AND MARKING ON PAGE 3

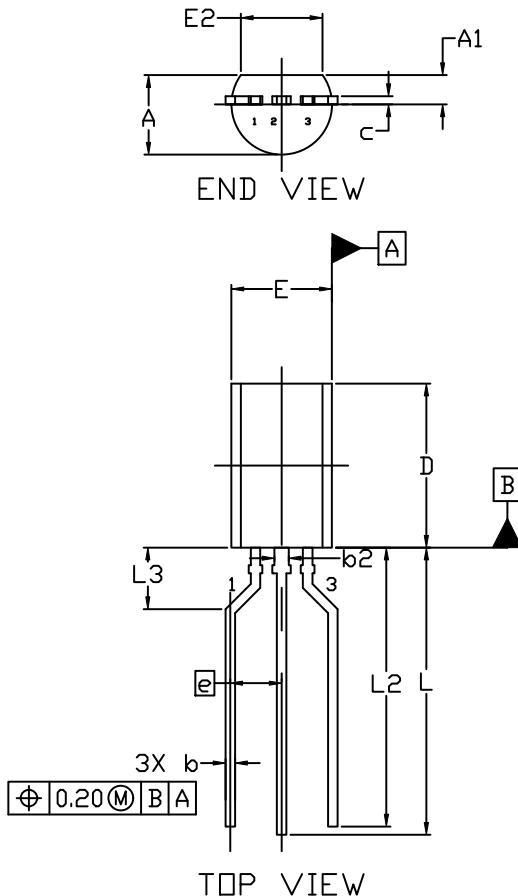
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**TO-92 (TO-226) 1 WATT**  
**CASE 29-10**  
**ISSUE D**

DATE 05 MAR 2021

**FORMED LEAD**




**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS.
4. DIMENSION b AND b2 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 0.20. DIMENSION b2 LOCATED ABOVE THE DAMBAR PORTION OF MIDDLE LEAD.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	3.75	3.90	4.05
A1	1.28	1.43	1.58
b	0.38	0.465	0.55
b2	0.62	0.70	0.78
c	0.35	0.40	0.45
D	7.85	8.00	8.15
E	4.75	4.90	5.05
E2	3.90	---	---
e	2.50 BSC		
L	13.80	14.00	14.20
L2	13.20	13.60	14.00
L3	3.00 REF		

**STYLES AND MARKING ON PAGE 3**

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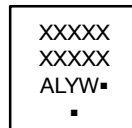
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**TO-92 (TO-226) 1 WATT**  
**CASE 29-10**  
**ISSUE D**

DATE 05 MAR 2021

STYLE 1: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 2: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 3: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 5: PIN 1. DRAIN 2. SOURCE 3. GATE
STYLE 6: PIN 1. GATE 2. SOURCE & SUBSTRATE 3. DRAIN	STYLE 7: PIN 1. SOURCE 2. DRAIN 3. GATE	STYLE 8: PIN 1. DRAIN 2. GATE 3. SOURCE & SUBSTRATE	STYLE 9: PIN 1. BASE 1 2. EMITTER 3. BASE 2	STYLE 10: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 11: PIN 1. ANODE 2. CATHODE & ANODE 3. CATHODE	STYLE 12: PIN 1. MAIN TERMINAL 1 2. GATE 3. MAIN TERMINAL 2	STYLE 13: PIN 1. ANODE 1 2. GATE 3. CATHODE 2	STYLE 14: PIN 1. EMITTER 2. COLLECTOR 3. BASE	STYLE 15: PIN 1. ANODE 1 2. CATHODE 3. ANODE 2
STYLE 16: PIN 1. ANODE 2. GATE 3. CATHODE	STYLE 17: PIN 1. COLLECTOR 2. BASE 3. EMITTER	STYLE 18: PIN 1. ANODE 2. CATHODE 3. NOT CONNECTED	STYLE 19: PIN 1. GATE 2. ANODE 3. CATHODE	STYLE 20: PIN 1. NOT CONNECTED 2. CATHODE 3. ANODE
STYLE 21: PIN 1. COLLECTOR 2. EMITTER 3. BASE	STYLE 22: PIN 1. SOURCE 2. GATE 3. DRAIN	STYLE 23: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 24: PIN 1. EMITTER 2. COLLECTOR/ANODE 3. CATHODE	STYLE 25: PIN 1. MT 1 2. GATE 3. MT 2
STYLE 26: PIN 1. V <sub>CC</sub> 2. GROUND 2 3. OUTPUT	STYLE 27: PIN 1. MT 2. SUBSTRATE 3. MT	STYLE 28: PIN 1. CATHODE 2. ANODE 3. GATE	STYLE 29: PIN 1. NOT CONNECTED 2. ANODE 3. CATHODE	STYLE 30: PIN 1. DRAIN 2. GATE 3. SOURCE
STYLE 31: PIN 1. GATE 2. DRAIN 3. SOURCE	STYLE 32: PIN 1. BASE 2. COLLECTOR 3. EMITTER	STYLE 33: PIN 1. RETURN 2. INPUT 3. OUTPUT	STYLE 34: PIN 1. INPUT 2. GROUND 3. LOGIC	STYLE 35: PIN 1. GATE 2. COLLECTOR 3. EMITTER

**GENERIC  
MARKING DIAGRAM\***




XXXX = Specific Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

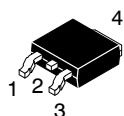
<b>DOCUMENT NUMBER:</b>	<b>98AON52857E</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>TO-92 (TO-226) 1 WATT</b>	<b>PAGE 3 OF 3</b>

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# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

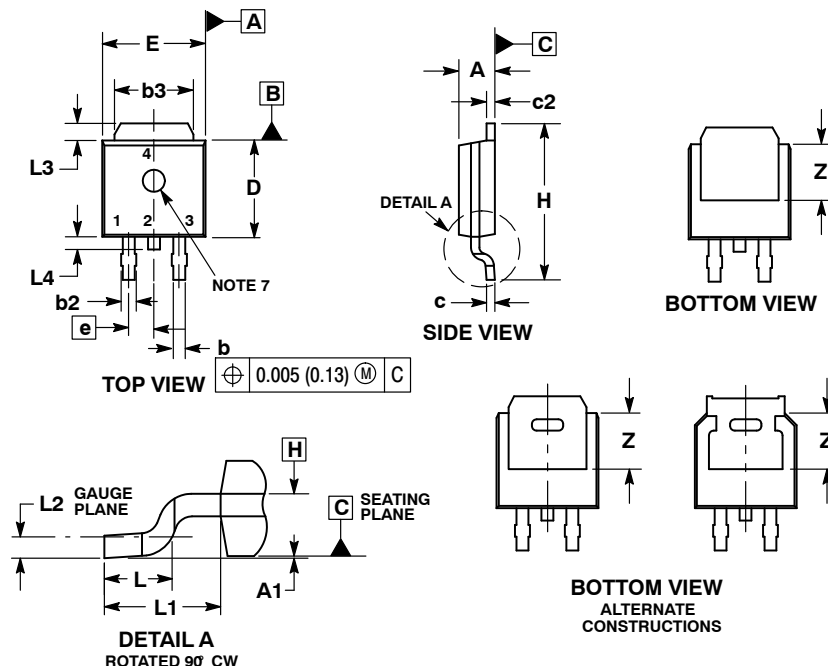
ON



SCALE 1:1

## DPAK (SINGLE GAUGE) CASE 369C ISSUE F

DATE 21 JUL 2015

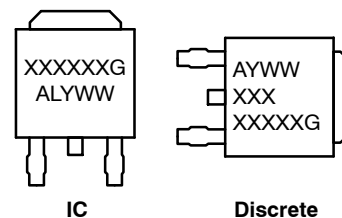


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.

DIM	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090	BSC	2.29	BSC
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114	REF	2.90	REF
L2	0.020	BSC	0.51	BSC
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

### GENERIC MARKING DIAGRAM\*

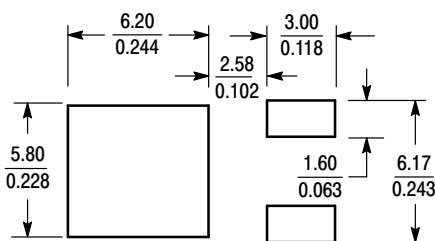


XXXXXX = Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.

- STYLE 1:**  
PIN 1. BASE  
2. COLLECTOR  
3. EMITTER  
4. COLLECTOR
- STYLE 2:**  
PIN 1. GATE  
2. DRAIN  
3. SOURCE  
4. DRAIN
- STYLE 3:**  
PIN 1. ANODE  
2. CATHODE  
3. ANODE  
4. CATHODE
- STYLE 4:**  
PIN 1. CATHODE  
2. ANODE  
3. GATE  
4. ANODE
- STYLE 5:**  
PIN 1. GATE  
2. ANODE  
3. CATHODE  
4. ANODE
- STYLE 6:**  
PIN 1. MT1  
2. MT2  
3. GATE  
4. MT2
- STYLE 7:**  
PIN 1. GATE  
2. COLLECTOR  
3. EMITTER  
4. COLLECTOR
- STYLE 8:**  
PIN 1. N/C  
2. CATHODE  
3. ANODE  
4. CATHODE
- STYLE 9:**  
PIN 1. ANODE  
2. CATHODE  
3. RESISTOR ADJUST  
4. CATHODE
- STYLE 10:**  
PIN 1. CATHODE  
2. ANODE  
3. CATHODE  
4. ANODE

### SOLDERING FOOTPRINT\*



SCALE 3:1 (mm inches)

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>DPAK (SINGLE GAUGE)</b>	<b>PAGE 1 OF 1</b>

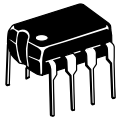
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# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

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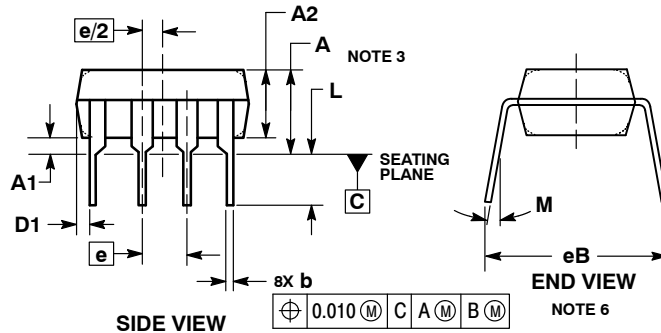
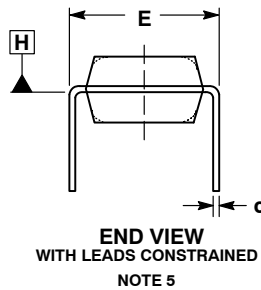
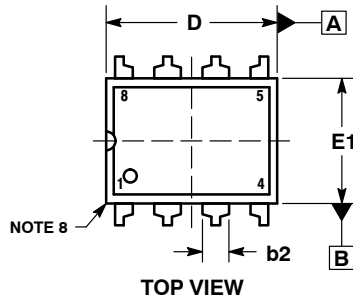
ON



SCALE 1:1

PDIP-8  
CASE 626-05  
ISSUE P

DATE 22 APR 2015

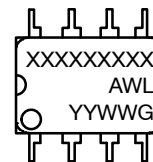


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
4. DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT TO EXCEED 0.10 INCH.
5. DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR TO DATUM C.
6. DIMENSION eB IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
7. DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE LEADS, WHERE THE LEADS EXIT THE BODY.
8. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE CORNERS).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	---	0.210	---	5.33
A1	0.015	---	0.38	---
A2	0.115	0.195	2.92	4.95
b	0.014	0.022	0.35	0.56
b2	0.060 TYP		1.52 TYP	
C	0.008	0.014	0.20	0.36
D	0.355	0.400	9.02	10.16
D1	0.005	---	0.13	---
E	0.300	0.325	7.62	8.26
E1	0.240	0.280	6.10	7.11
e	0.100 BSC		2.54 BSC	
eB	---	0.430	---	10.92
L	0.115	0.150	2.92	3.81
M	---	10°	---	10°

### GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot  
YY = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

### STYLE 1:

- PIN 1: AC IN  
2. DC + IN  
3. DC - IN  
4. AC IN  
5. GROUND  
6. OUTPUT  
7. AUXILIARY  
8. V<sub>CC</sub>

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# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

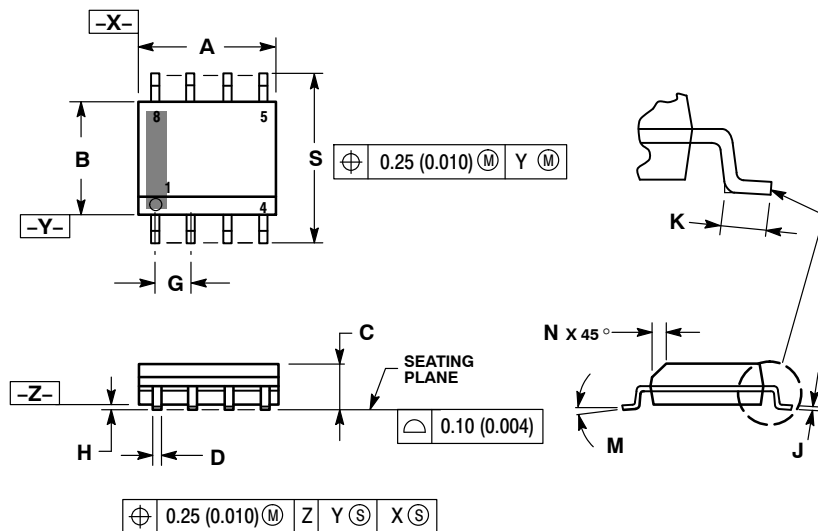
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SCALE 1:1

**SOIC-8 NB**  
CASE 751-07  
ISSUE AK

DATE 16 FEB 2011

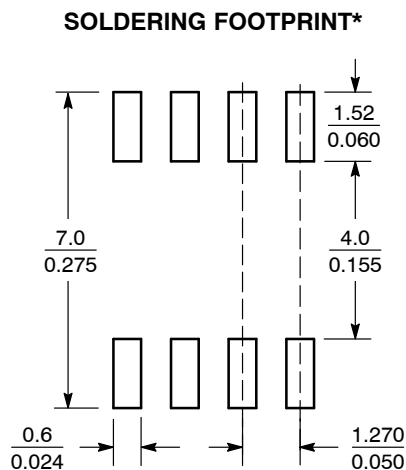


### NOTES:

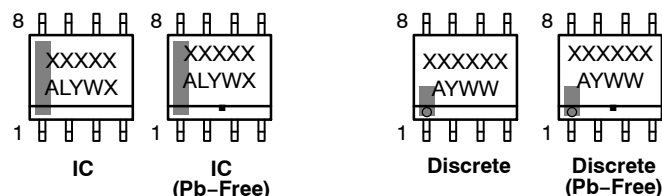
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

### GENERIC MARKING DIAGRAM\*



SCALE 6:1 (mm/inches)



XXXXXX = Specific Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

XXXXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
▪ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### STYLES ON PAGE 2

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DESCRIPTION:	SOIC-8 NB	PAGE 1 OF 2


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**SOIC-8 NB**  
**CASE 751-07**  
**ISSUE AK**

DATE 16 FEB 2011

<b>STYLE 1:</b> PIN 1. EMITTER 2. COLLECTOR 3. COLLECTOR 4. EMITTER 5. EMITTER 6. BASE 7. BASE 8. EMITTER	<b>STYLE 2:</b> PIN 1. COLLECTOR, DIE, #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. BASE, #2 6. EMITTER, #2 7. BASE, #1 8. EMITTER, #1	<b>STYLE 3:</b> PIN 1. DRAIN, DIE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. GATE, #2 6. SOURCE, #2 7. GATE, #1 8. SOURCE, #1	<b>STYLE 4:</b> PIN 1. ANODE 2. ANODE 3. ANODE 4. ANODE 5. ANODE 6. ANODE 7. ANODE 8. COMMON CATHODE
<b>STYLE 5:</b> PIN 1. DRAIN 2. DRAIN 3. DRAIN 4. DRAIN 5. GATE 6. GATE 7. SOURCE 8. SOURCE	<b>STYLE 6:</b> PIN 1. SOURCE 2. DRAIN 3. DRAIN 4. SOURCE 5. SOURCE 6. GATE 7. GATE 8. SOURCE	<b>STYLE 7:</b> PIN 1. INPUT 2. EXTERNAL BYPASS 3. THIRD STAGE SOURCE 4. GROUND 5. DRAIN 6. GATE 3 7. SECOND STAGE Vd 8. FIRST STAGE Vd	<b>STYLE 8:</b> PIN 1. COLLECTOR, DIE #1 2. BASE, #1 3. BASE, #2 4. COLLECTOR, #2 5. COLLECTOR, #2 6. EMITTER, #2 7. EMITTER, #1 8. COLLECTOR, #1
<b>STYLE 9:</b> PIN 1. EMITTER, COMMON 2. COLLECTOR, DIE #1 3. COLLECTOR, DIE #2 4. EMITTER, COMMON 5. EMITTER, COMMON 6. BASE, DIE #2 7. BASE, DIE #1 8. EMITTER, COMMON	<b>STYLE 10:</b> PIN 1. GROUND 2. BIAS 1 3. OUTPUT 4. GROUND 5. GROUND 6. BIAS 2 7. INPUT 8. GROUND	<b>STYLE 11:</b> PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. DRAIN 2 7. DRAIN 1 8. DRAIN 1	<b>STYLE 12:</b> PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN
<b>STYLE 13:</b> PIN 1. N.C. 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN	<b>STYLE 14:</b> PIN 1. N-SOURCE 2. N-GATE 3. P-SOURCE 4. P-GATE 5. P-DRAIN 6. P-DRAIN 7. N-DRAIN 8. N-DRAIN	<b>STYLE 15:</b> PIN 1. ANODE 1 2. ANODE 1 3. ANODE 1 4. ANODE 1 5. CATHODE, COMMON 6. CATHODE, COMMON 7. CATHODE, COMMON 8. CATHODE, COMMON	<b>STYLE 16:</b> PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2 4. BASE, DIE #2 5. COLLECTOR, DIE #2 6. COLLECTOR, DIE #2 7. COLLECTOR, DIE #1 8. COLLECTOR, DIE #1
<b>STYLE 17:</b> PIN 1. VCC 2. V2OUT 3. V1OUT 4. TXE 5. RXE 6. VEE 7. GND 8. ACC	<b>STYLE 18:</b> PIN 1. ANODE 2. ANODE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. CATHODE 8. CATHODE	<b>STYLE 19:</b> PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. MIRROR 2 7. DRAIN 1 8. MIRROR 1	<b>STYLE 20:</b> PIN 1. SOURCE (N) 2. GATE (N) 3. SOURCE (P) 4. GATE (P) 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN
<b>STYLE 21:</b> PIN 1. CATHODE 1 2. CATHODE 2 3. CATHODE 3 4. CATHODE 4 5. CATHODE 5 6. COMMON ANODE 7. COMMON ANODE 8. CATHODE 6	<b>STYLE 22:</b> PIN 1. I/O LINE 1 2. COMMON CATHODE/VCC 3. COMMON CATHODE/VCC 4. I/O LINE 3 5. COMMON ANODE/GND 6. I/O LINE 4 7. I/O LINE 5 8. COMMON ANODE/GND	<b>STYLE 23:</b> PIN 1. LINE 1 IN 2. COMMON ANODE/GND 3. COMMON ANODE/GND 4. LINE 2 IN 5. LINE 2 OUT 6. COMMON ANODE/GND 7. COMMON ANODE/GND 8. LINE 1 OUT	<b>STYLE 24:</b> PIN 1. BASE 2. EMITTER 3. COLLECTOR/ANODE 4. COLLECTOR/ANODE 5. CATHODE 6. CATHODE 7. COLLECTOR/ANODE 8. COLLECTOR/ANODE
<b>STYLE 25:</b> PIN 1. VIN 2. N/C 3. REXT 4. GND 5. IOUT 6. IOUT 7. IOUT 8. IOUT	<b>STYLE 26:</b> PIN 1. GND 2. dv/dt 3. ENABLE 4. ILIMIT 5. SOURCE 6. SOURCE 7. SOURCE 8. VCC	<b>STYLE 27:</b> PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ 5. SOURCE 6. SOURCE 7. SOURCE 8. DRAIN	<b>STYLE 28:</b> PIN 1. SW_TO_GND 2. DASIC_OFF 3. DASIC_SW_DET 4. GND 5. V_MON 6. VBULK 7. VBULK 8. VIN
<b>STYLE 29:</b> PIN 1. BASE, DIE #1 2. EMITTER, #1 3. BASE, #2 4. EMITTER, #2 5. COLLECTOR, #2 6. COLLECTOR, #2 7. COLLECTOR, #1 8. COLLECTOR, #1	<b>STYLE 30:</b> PIN 1. DRAIN 1 2. DRAIN 1 3. GATE 2 4. SOURCE 2 5. SOURCE 1/DRAIN 2 6. SOURCE 1/DRAIN 2 7. SOURCE 1/DRAIN 2 8. GATE 1		

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# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

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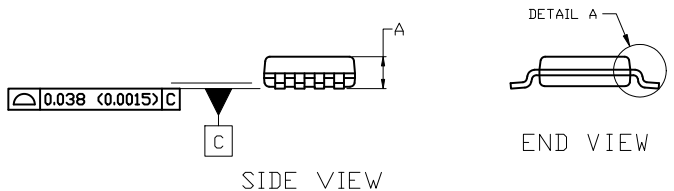
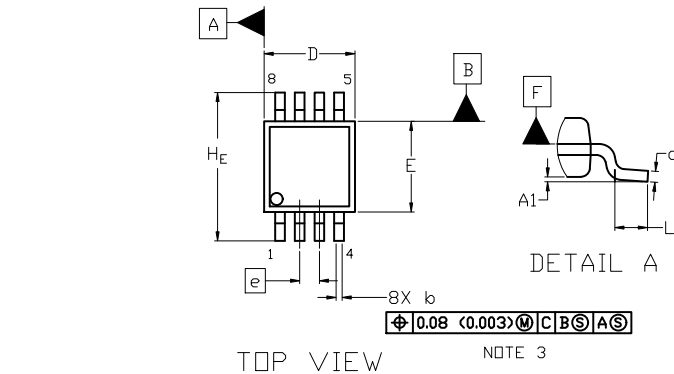
ON



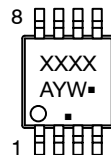
SCALE 2:1

## Micro8 CASE 846A-02 ISSUE K

DATE 16 JUL 2020



### GENERIC MARKING DIAGRAM\*



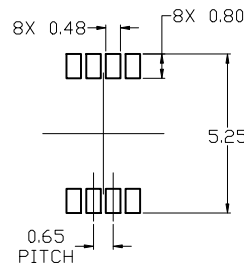
XXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSION E DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 mm PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
5. DATUMS A AND B ARE TO BE DETERMINED AT DATUM F.
6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, [SOLDERM-10](#).

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	1.10
A1	0.05	0.08	0.15
b	0.25	0.33	0.40
c	0.13	0.18	0.23
D	2.90	3.00	3.10
E	2.90	3.00	3.10
e	0.65 BSC		
H <sub>E</sub>	4.75	4.90	5.05
L	0.40	0.55	0.70

### STYLE 1:

- PIN 1. SOURCE
- SOURCE
- SOURCE
- GATE
- DRAIN
- DRAIN
- DRAIN
- DRAIN

### STYLE 2:

- PIN 1. SOURCE 1
- GATE 1
- SOURCE 2
- GATE 2
- DRAIN 2
- DRAIN 2
- DRAIN 1
- DRAIN 1

### STYLE 3:

- PIN 1. N-SOURCE
- N-GATE
- P-SOURCE
- P-GATE
- P-DRAIN
- P-DRAIN
- N-DRAIN
- N-DRAIN

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